

WIRE BONDER AND WIRE BONDING METHOD**ABSTRACT**

The present invention provides an apparatus and its method that is able to effectively use positional data such as coordinates and so forth stored in advance in a bonder.

This wire bonder is able to compare and evaluate at least one set of image data of either a first bonding point or second bonding point in the form of bonded sites, or a wire spread between said first and second bonding points, with the positional data into which said image data has been incorporated in advance, and automatically perform inspection and make corrections.

(Fig. 1)